



W
A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Confirmation No.: 7118

Osamu FURUKAWA et al.

Group Art Unit: 2841

Application No.: 10/615,298

Examiner: Ivan CARPIO

Filed: July 9, 2003

Attorney Docket No.: 108066-00087

For: SURFACE-MOUNTED ELECTRONIC COMPONENT MODULE AND METHOD
FOR MANUFACTURING THE SAME

RESPONSE TO FINAL REJECTION UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 1, 2007

Sir:

The Office Action dated February 23, 2007, has been received and carefully noted. The following remarks are being submitted as a full and complete response thereto. Reconsideration of the application is respectfully requested in light of the following remarks. Claims 1, 3, 5, 7, 9 and 10 are pending in this application.

The Office Action rejects claims 1 and 9 under 35 U.S.C. § 103(a) over Huang (U.S. Patent No. 6,777,819) in view of Kemmochi et al. (U.S. Patent Application Publication No. 2004/0032706); claim 3 under 35 U.S.C. § 103(a) over Huang in view of Kemmochi and Fujimoto et al. (U.S. Patent Application Publication No. 2001/0006456); claim 5 under 35 U.S.C. § 103(a) over Yamada et al. (U.S. Patent No. 6,784,765) in view of Huang and Kemmochi; and claim 7 under 35 U.S.C. § 103(a) over Yamada, Huang, Kemmochi and further in view of Fujimoto. The rejections are respectfully traversed.